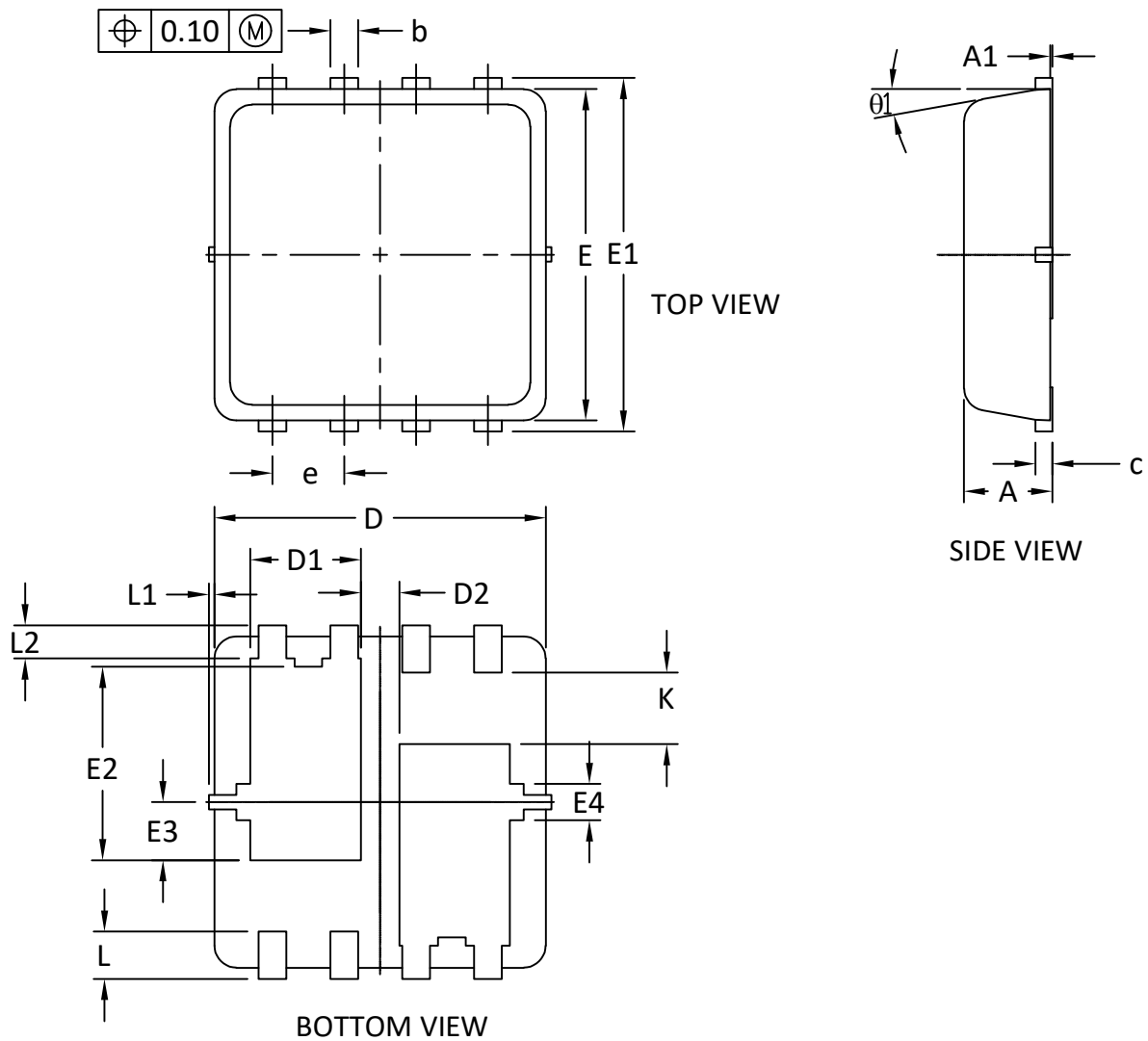
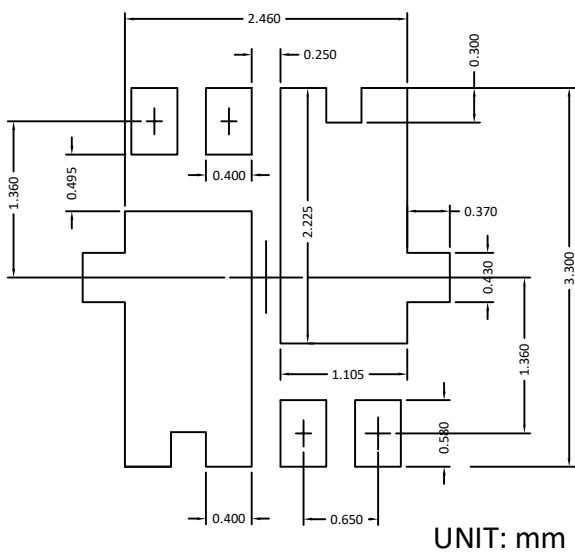




DFN3x3\_8L\_EP2\_P PACKAGE OUTLINE



RECOMMENDED LAND PATTERN



SYMBOLS	DIM. IN MM			DIM. IN INCH		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.700	0.800	0.900	0.028	0.031	0.035
A1	0.000	---	0.050	0.000	---	0.002
b	0.240	0.250	0.300	0.009	0.010	0.012
c	0.100	0.150	0.250	0.004	0.006	0.010
D	2.900	3.000	3.100	0.114	0.118	0.122
D1	0.850	1.000	1.150	0.033	0.039	0.045
D2	0.250	0.350	0.450	0.010	0.014	0.018
E	2.900	3.000	3.100	0.114	0.118	0.122
E1	3.050	3.200	3.350	0.120	0.126	0.132
E2	1.550	1.750	1.950	0.061	0.069	0.077
E3	0.430	0.530	0.630	0.017	0.021	0.025
E4	0.280	0.330	0.380	0.011	0.013	0.015
e	0.600	0.650	0.700	0.024	0.026	0.028
K	0.450	0.650	0.850	0.018	0.026	0.033
L	0.330	0.430	0.530	0.013	0.017	0.021
L1	0.000	---	0.100	0.000	---	0.004
L2	0.250	0.300	0.350	0.010	0.012	0.014
θ1	0°	10°	12°	0°	10°	12°

NOTE

1. PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.  
MOLD FLASH AT THE NON-LEAD SIDES SHOULD BE LESS THAN 6 MILS EACH.
2. CONTROLLING DIMENSION IS MILLIMETER.  
CONVERTED INCH DIMENSIONS ARE NOT NECESSARILY EXACT.
3. THIS PACKAGE WAS QUALIFIED USING IR REFLOW PROCESS (JEDEC STANDARD). FOR USAGE IN OTHER SOLDERING PROCESSES, PLEASE CONTACT LOCAL AOS REPRESENTATIVES.